



# SOT96-1

plastic small outline package; 8 leads; body width 3.9 mm

8 February 2016

Package information

## 1. Package summary

Terminal position code	D (double)
Package type descriptive code	SO8
Package type industry code	SO8
Package style descriptive code	SO (small outline)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	076E03
JEDEC package outline code	MS-012
Mounting method type	S (surface mount)
Issue date	18-2-2003

Table 1. Package summary

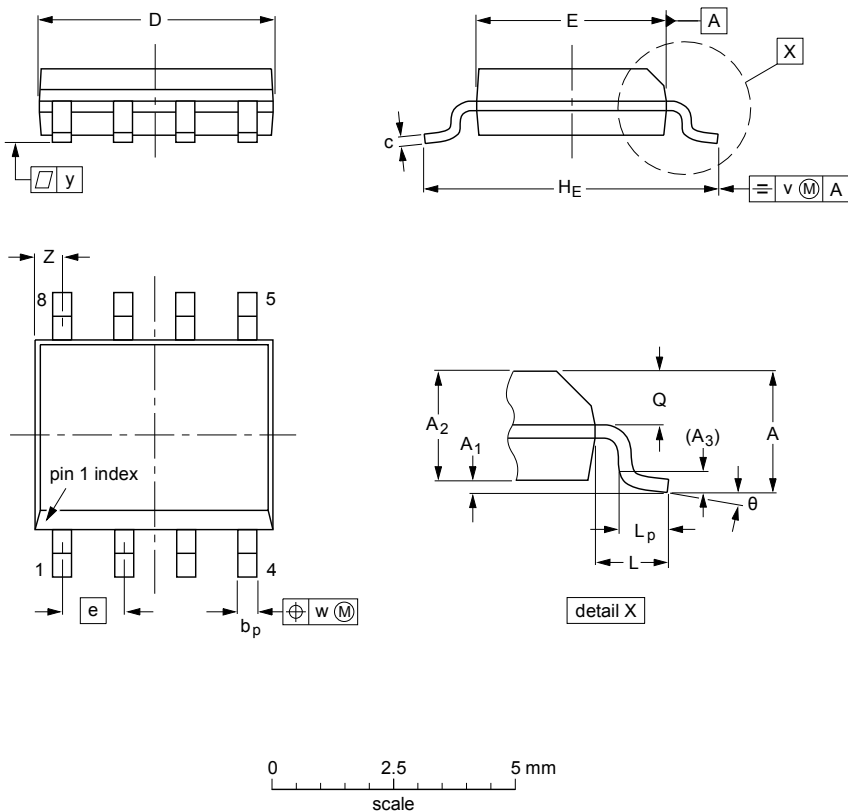
Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		4.8	-	4.9	5	mm
E	package width		3.8	-	3.9	4	mm
A	seated height		[tbd]	-	1.75	1.75	mm
A <sub>2</sub>	package height		1.25	-	1.35	1.45	mm
n <sub>2</sub>	actual quantity of termination		-	-	8	-	



2. Package outline

SO8: plastic small outline package; 8 leads; body width 3.9 mm

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DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(2)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	5.0 4.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.20 0.19	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

- Notes
- 1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.
  - 2. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT96-1	076E03	MS-012				99-12-27 03-02-18

Fig. 1. Package outline SO8 (SOT96-1)

3. Soldering

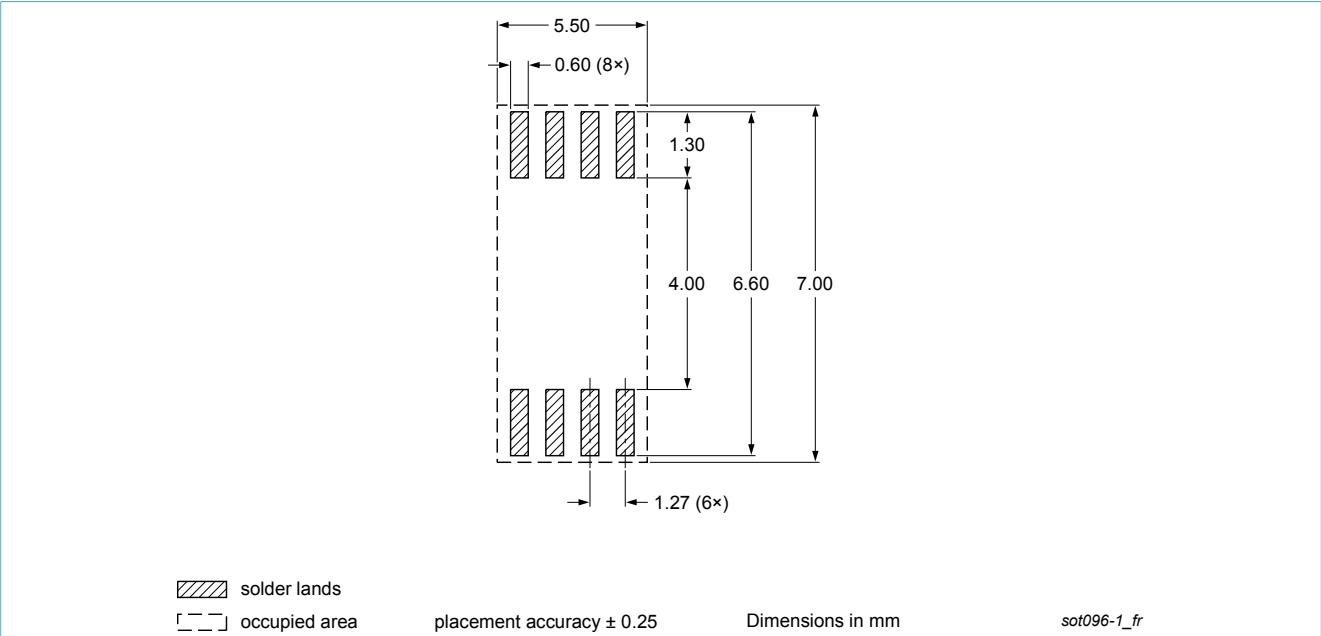


Fig. 2. Reflow soldering footprint for SO8 (SOT96-1)

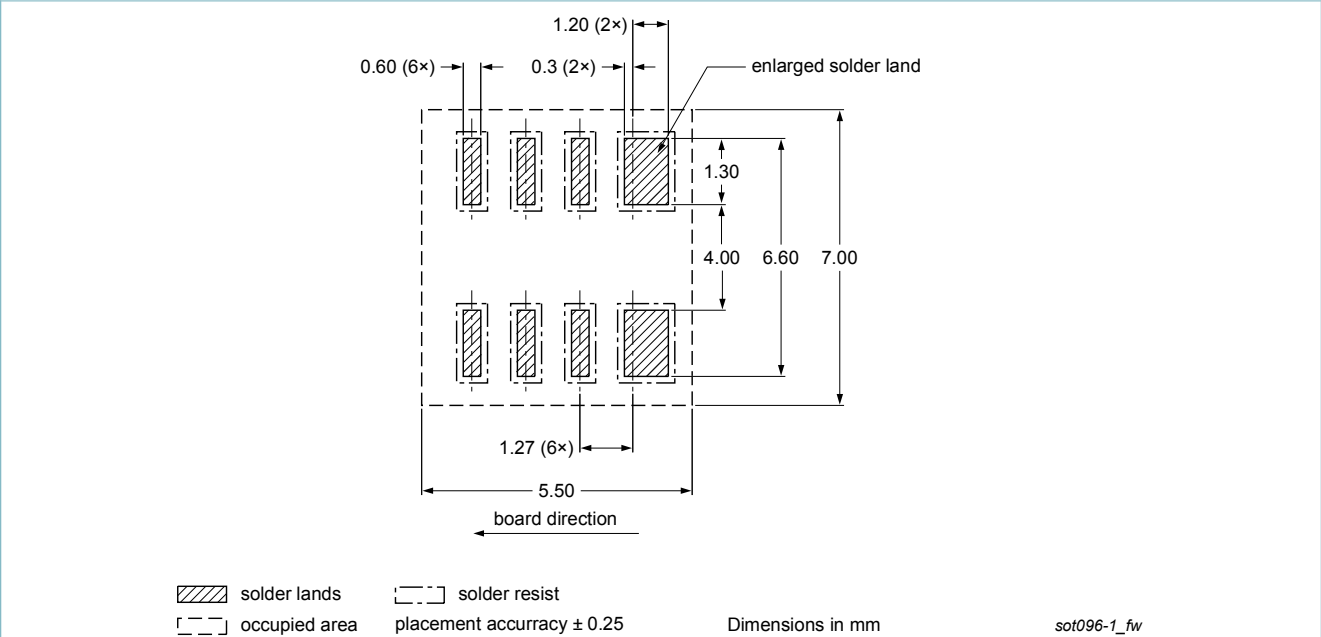


Fig. 3. Wave soldering footprint for SO8 (SOT96-1)

## 4. Legal information

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